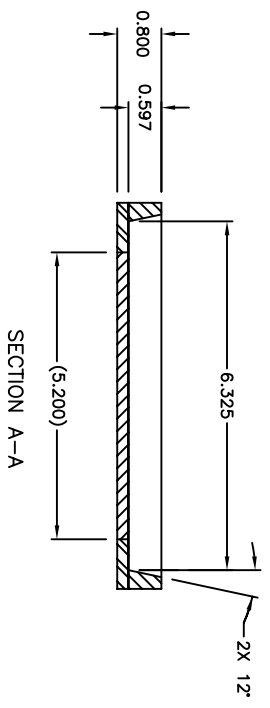
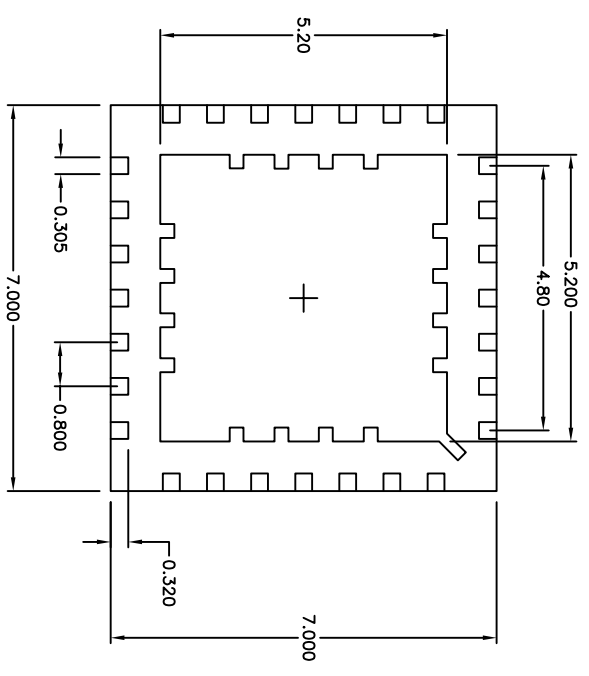
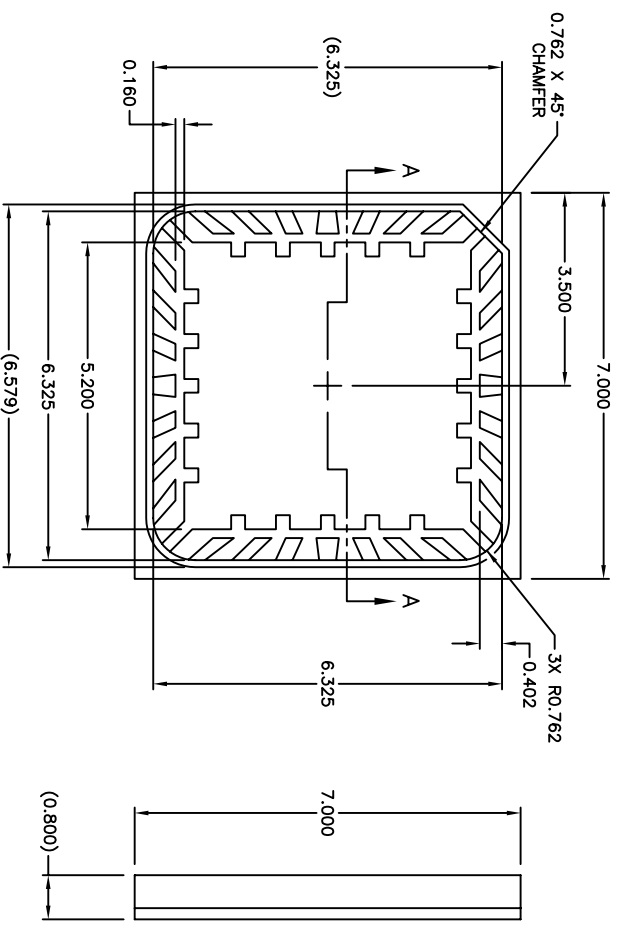


REVISIONS			APPROVED
ECN NO.	DATE	DESCRIPTION	
10495	11/06/05	PRODUCTION RELEASE	D.BENANDIO



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FRAME: COPPER, 194 FH.
  3. LEAD FINISH: FULL GOLD PLATE.
  4. FRAME THICKNESS: 0.2030 ±.0076.
  5. DIE PAD: 5.200 X 5.200.
  6. DIE PAD: 5.200 X 5.200.
  7. JEDEC OUTLINE: MO-220 (VKKB).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± --- X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	11/05/05
CHKD BY	P. FLASKERUD	DATE	11/05/05

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**SEMPAC, INC.**  
 Open-Pak™ Technologies  
 www.sempac.com  
 568 E. WEDDELL DRIVE, SUITE 5  
 SUNNYVALE, CALIFORNIA 94089  
 PHONE: (408) 400-9002 FAX: (408) 400-9006

28 Lead 7mm x 7mm  
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP7X7-28-OP-01	4
SCALE	NONE	
CAD FILE	MLP7X7-28-OP-01-R4.DWG	
SHEET	1 OF 1	